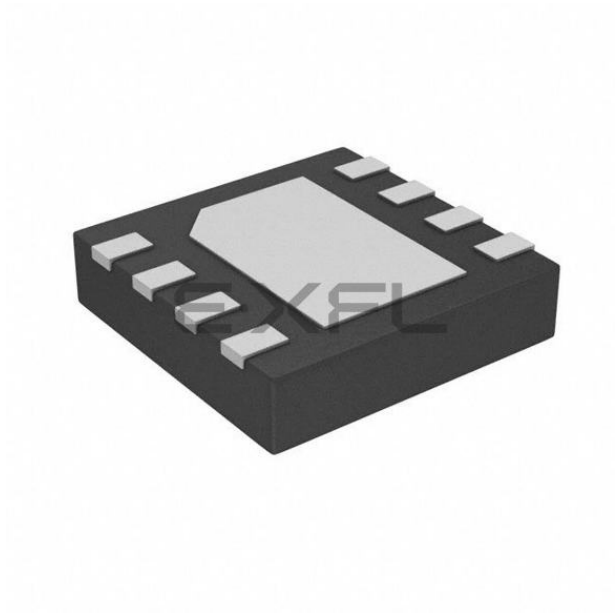

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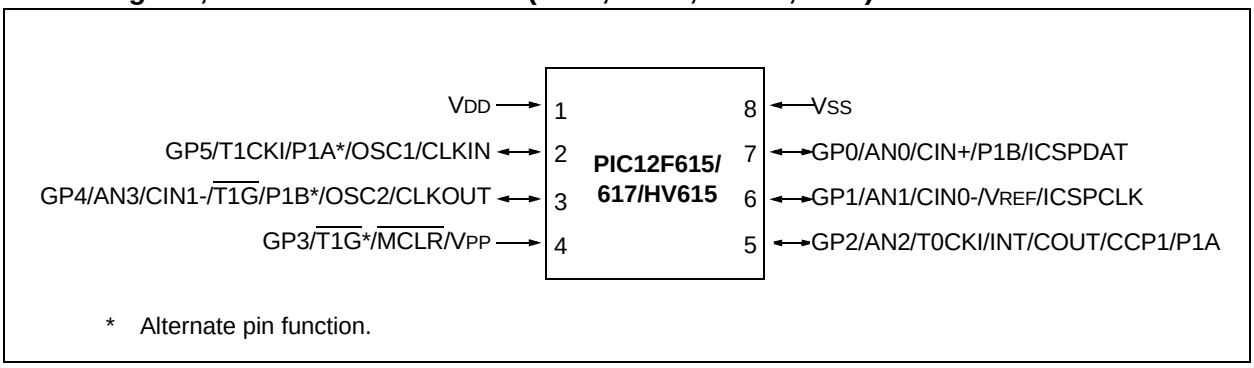
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	5
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12hv609-i-mf

8-Pin Diagram, PIC12F615/617/HV615 (PDIP, SOIC, MSOP, DFN)



* Alternate pin function.

TABLE 2: PIC12F615/617/HV615 PIN SUMMARY (PDIP, SOIC, MSOP, DFN)

I/O	Pin	Analog	Comparators	Timer	CCP	Interrupts	Pull-ups	Basic
GP0	7	AN0	CIN+	—	P1B	IOC	Y	ICSPDAT
GP1	6	AN1	CIN0-	—	—	IOC	Y	ICSPCLK/VREF
GP2	5	AN2	COUT	T0CKI	CCP1/P1A	INT/IOC	Y	—
GP3(1)	4	—	—	T1G*	—	IOC	Y(2)	MCLR/VPP
GP4	3	AN3	CIN1-	T1G	P1B*	IOC	Y	OSC2/CLKOUT
GP5	2	—	—	T1CKI	P1A*	IOC	Y	OSC1/CLKIN
—	1	—	—	—	—	—	—	VDD
—	8	—	—	—	—	—	—	VSS

* Alternate pin function.

Note 1: Input only.

2: Only when pin is configured for external MCLR.

2.2.2.1 STATUS Register

The STATUS register, shown in Register 2-1, contains:

- the arithmetic status of the ALU
- the Reset status
- the bank select bits for data memory (RAM)

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS,` will clear the upper three bits and set the Z bit. This leaves the STATUS register as `'000u u1uu'` (where u = unchanged).

It is recommended, therefore, that only `BCF, BSF, SWAPF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect any Status bits. For other instructions not affecting any Status bits, see the **Section 14.0 "Instruction Set Summary"**.

Note 1:	Bits IRP and RP1 of the STATUS register are not used by the PIC12F609/615/617/12HV609/615 and should be maintained as clear. Use of these bits is not recommended, since this may affect upward compatibility with future products.
2:	The C and DC bits operate as a $\overline{Borrow}$ and Digit $\overline{Borrow}$ out bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

REGISTER 2-1: STATUS: STATUS REGISTER

Reserved	Reserved	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **IRP:** This bit is reserved and should be maintained as '0'

bit 6 **RP1:** This bit is reserved and should be maintained as '0'

bit 5 **RP0:** Register Bank Select bit (used for direct addressing)
1 = Bank 1 (80h – FFh)
0 = Bank 0 (00h – 7Fh)

bit 4 **$\overline{TO}$:** Time-out bit
1 = After power-up, `CLRWDT` instruction or `SLEEP` instruction
0 = A WDT time-out occurred

bit 3 **$\overline{PD}$:** Power-down bit
1 = After power-up or by the `CLRWDT` instruction
0 = By execution of the `SLEEP` instruction

bit 2 **Z:** Zero bit
1 = The result of an arithmetic or logic operation is zero
0 = The result of an arithmetic or logic operation is not zero

bit 1 **DC:** Digit Carry/$\overline{Borrow}$ bit (`ADDWF, ADDLW, SUBLW, SUBWF` instructions), For $\overline{Borrow}$, the polarity is reversed.
1 = A carry-out from the 4th low-order bit of the result occurred
0 = No carry-out from the 4th low-order bit of the result

bit 0 **C:** Carry/$\overline{Borrow}$ bit(1) (`ADDWF, ADDLW, SUBLW, SUBWF` instructions)
1 = A carry-out from the Most Significant bit of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note 1: For $\overline{Borrow}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF, RLF`) instructions, this bit is loaded with either the high-order or low-order bit of the source register.

2.2.2.3 INTCON Register

The INTCON register is a readable and writable register, which contains the various enable and flag bits for TMR0 register overflow, GPIO change and external GP2/INT pin interrupts.

Note:	Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 2-3: INTCON: INTERRUPT CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
GIE	PEIE	T0IE	INTE	GPIE	T0IF	INTF	GPIF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **GIE:** Global Interrupt Enable bit
1 = Enables all unmasked interrupts
0 = Disables all interrupts

bit 6 **PEIE:** Peripheral Interrupt Enable bit
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts

bit 5 **T0IE:** Timer0 Overflow Interrupt Enable bit
1 = Enables the Timer0 interrupt
0 = Disables the Timer0 interrupt

bit 4 **INTE:** GP2/INT External Interrupt Enable bit
1 = Enables the GP2/INT external interrupt
0 = Disables the GP2/INT external interrupt

bit 3 **GPIE:** GPIO Change Interrupt Enable bit(1)
1 = Enables the GPIO change interrupt
0 = Disables the GPIO change interrupt

bit 2 **T0IF:** Timer0 Overflow Interrupt Flag bit(2)
1 = Timer0 register has overflowed (must be cleared in software)
0 = Timer0 register did not overflow

bit 1 **INTF:** GP2/INT External Interrupt Flag bit
1 = The GP2/INT external interrupt occurred (must be cleared in software)
0 = The GP2/INT external interrupt did not occur

bit 0 **GPIF:** GPIO Change Interrupt Flag bit
1 = When at least one of the GPIO <5:0> pins changed state (must be cleared in software)
0 = None of the GPIO <5:0> pins have changed state

Note 1: IOC register must also be enabled.
2: T0IF bit is set when TMR0 rolls over. TMR0 is unchanged on Reset and should be initialized before clearing T0IF bit.

4.0 OSCILLATOR MODULE

4.1 Overview

The Oscillator module has a wide variety of clock sources and selection features that allow it to be used in a wide range of applications while maximizing performance and minimizing power consumption. Figure 4-1 illustrates a block diagram of the Oscillator module.

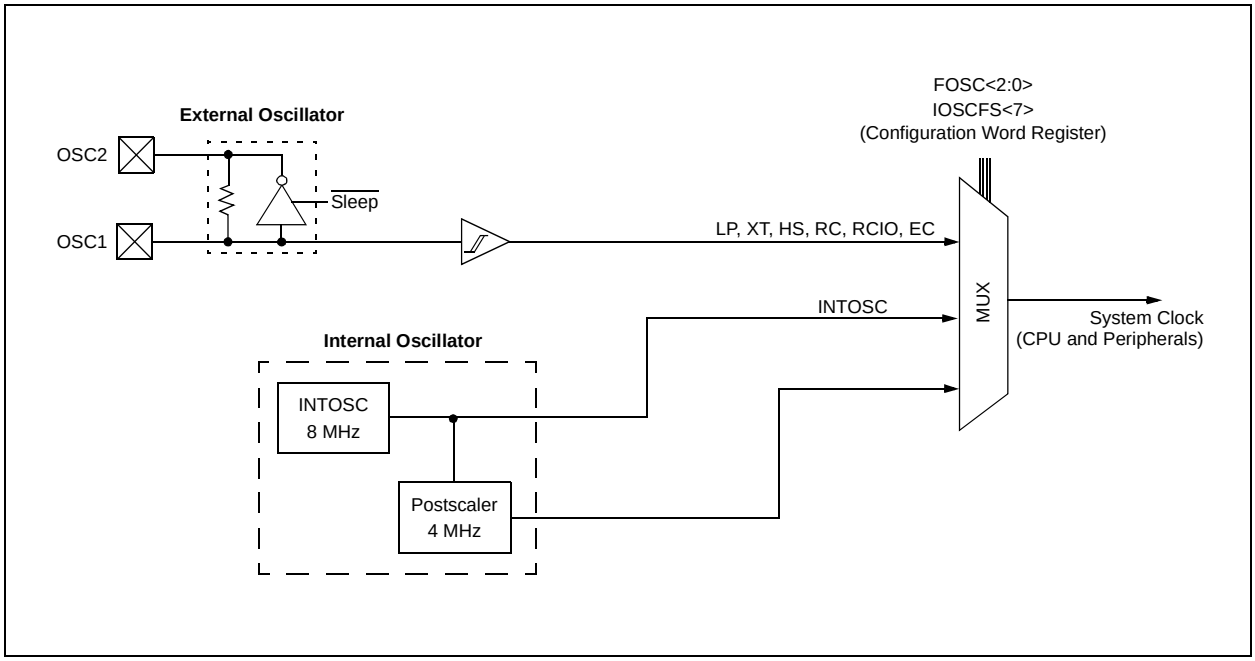
Clock sources can be configured from external oscillators, quartz crystal resonators, ceramic resonators and Resistor-Capacitor (RC) circuits. In addition, the system clock source can be configured with a choice of two selectable speeds: internal or external system clock source.

The Oscillator module can be configured in one of eight clock modes.

3. EC – External clock with I/O on OSC2/CLKOUT.
4. LP – 32 kHz Low-Power Crystal mode.
5. XT – Medium Gain Crystal or Ceramic Resonator Oscillator mode.
6. HS – High Gain Crystal or Ceramic Resonator mode.
7. RC – External Resistor-Capacitor (RC) with FOSC/4 output on OSC2/CLKOUT.
8. RCIO – External Resistor-Capacitor (RC) with I/O on OSC2/CLKOUT.
9. INTOSC – Internal oscillator with FOSC/4 output on OSC2 and I/O on OSC1/CLKIN.
10. INTOSCIO – Internal oscillator with I/O on OSC1/CLKIN and OSC2/CLKOUT.

Clock Source modes are configured by the FOSC<2:0> bits in the Configuration Word register (CONFIG). The Internal Oscillator module provides a selectable system clock mode of either 4 MHz (Postscaler) or 8 MHz (INTOSC).

FIGURE 4-1: PIC® MCU CLOCK SOURCE BLOCK DIAGRAM



7.0 TIMER1 MODULE WITH GATE CONTROL

The Timer1 module is a 16-bit timer/counter with the following features:

- 16-bit timer/counter register pair (TMR1H:TMR1L)
- Programmable internal or external clock source
- 3-bit prescaler
- Optional LP oscillator
- Synchronous or asynchronous operation
- Timer1 gate (count enable) via comparator or $\overline{T1G}$ pin
- Interrupt on overflow
- Wake-up on overflow (external clock, Asynchronous mode only)
- Time base for the Capture/Compare function
- Special Event Trigger (with ECCP)
- Comparator output synchronization to Timer1 clock

Figure 7-1 is a block diagram of the Timer1 module.

7.1 Timer1 Operation

The Timer1 module is a 16-bit incrementing counter which is accessed through the TMR1H:TMR1L register pair. Writes to TMR1H or TMR1L directly update the counter.

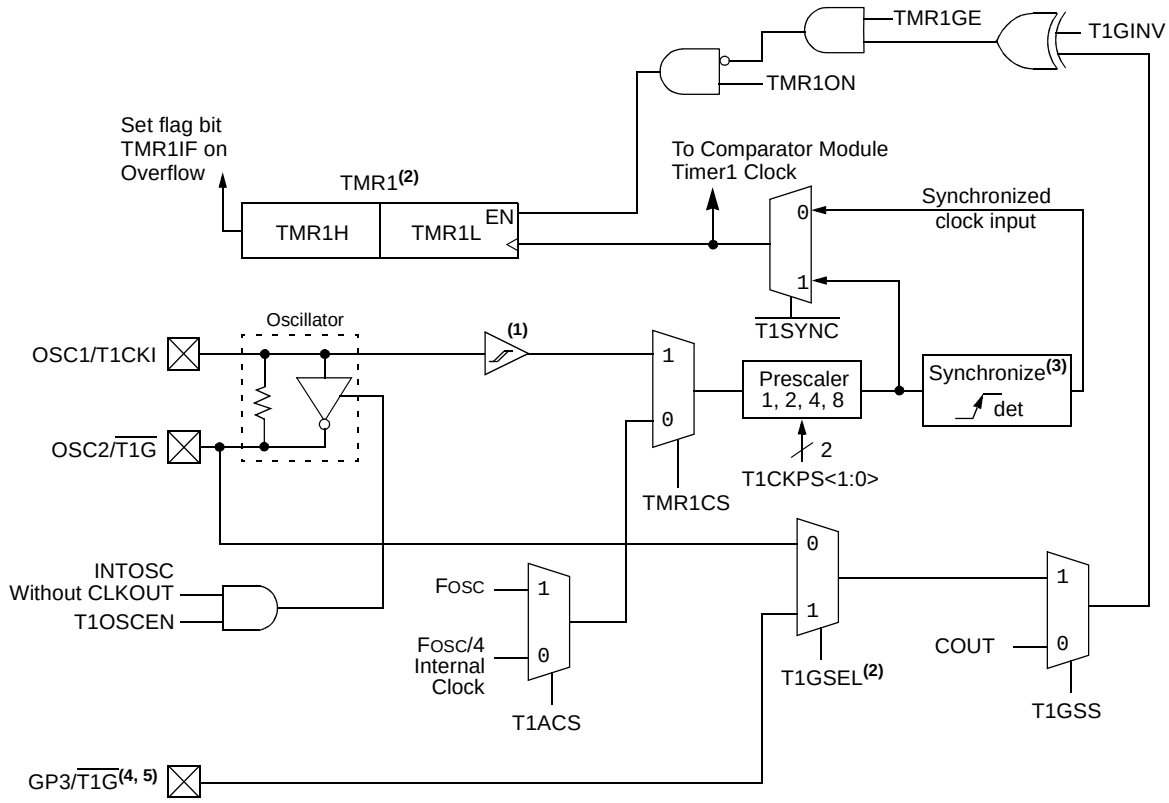
When used with an internal clock source, the module is a timer. When used with an external clock source, the module can be used as either a timer or counter.

7.2 Clock Source Selection

The TMR1CS bit of the T1CON register is used to select the clock source. When TMR1CS = 0, the clock source is FOSC/4. When TMR1CS = 1, the clock source is supplied externally.

Clock Source	TMR1CS	T1ACS
FOSC/4	0	0
FOSC	0	1
T1CKI pin	1	x

FIGURE 7-1: TIMER1 BLOCK DIAGRAM



Note 1: ST Buffer is low power type when using LP oscillator, or high speed type when using T1CKI.
2: Timer1 register increments on rising edge.
3: Synchronize does not operate while in Sleep.
4: Alternate pin function.
5: PIC12F615/617/HV615 only.

REGISTER 8-1: T2CON: TIMER 2 CONTROL REGISTER

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **Unimplemented:** Read as '0'

bit 6-3 **TOUTPS<3:0>:** Timer2 Output Postscaler Select bits
0000 =1:1 Postscaler
0001 =1:2 Postscaler
0010 =1:3 Postscaler
0011 =1:4 Postscaler
0100 =1:5 Postscaler
0101 =1:6 Postscaler
0110 =1:7 Postscaler
0111 =1:8 Postscaler
1000 =1:9 Postscaler
1001 =1:10 Postscaler
1010 =1:11 Postscaler
1011 =1:12 Postscaler
1100 =1:13 Postscaler
1101 =1:14 Postscaler
1110 =1:15 Postscaler
1111 =1:16 Postscaler

bit 2 **TMR2ON:** Timer2 On bit
1 = Timer2 is on
0 = Timer2 is off

bit 1-0 **T2CKPS<1:0>:** Timer2 Clock Prescale Select bits
00 =Prescaler is 1
01 =Prescaler is 4
1x =Prescaler is 16

TABLE 8-1: SUMMARY OF REGISTERS ASSOCIATED WITH TIMER2

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	GPIE	T0IF	INTF	GPIF	0000 0000	0000 0000
PIE1	—	ADIE(1)	CCP1IE(1)	—	CMIE	—	TMR2IE(1)	TMR1IE	-00- 0-00	-00- 0-00
PIR1	—	ADIF(1)	CCP1IF(1)	—	CMIF	—	TMR2IF(1)	TMR1IF	-00- 0-00	-00- 0-00
PR2(1)	Timer2 Module Period Register								1111 1111	1111 1111
TMR2(1)	Holding Register for the 8-bit TMR2 Register								0000 0000	0000 0000
T2CON(1)	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000

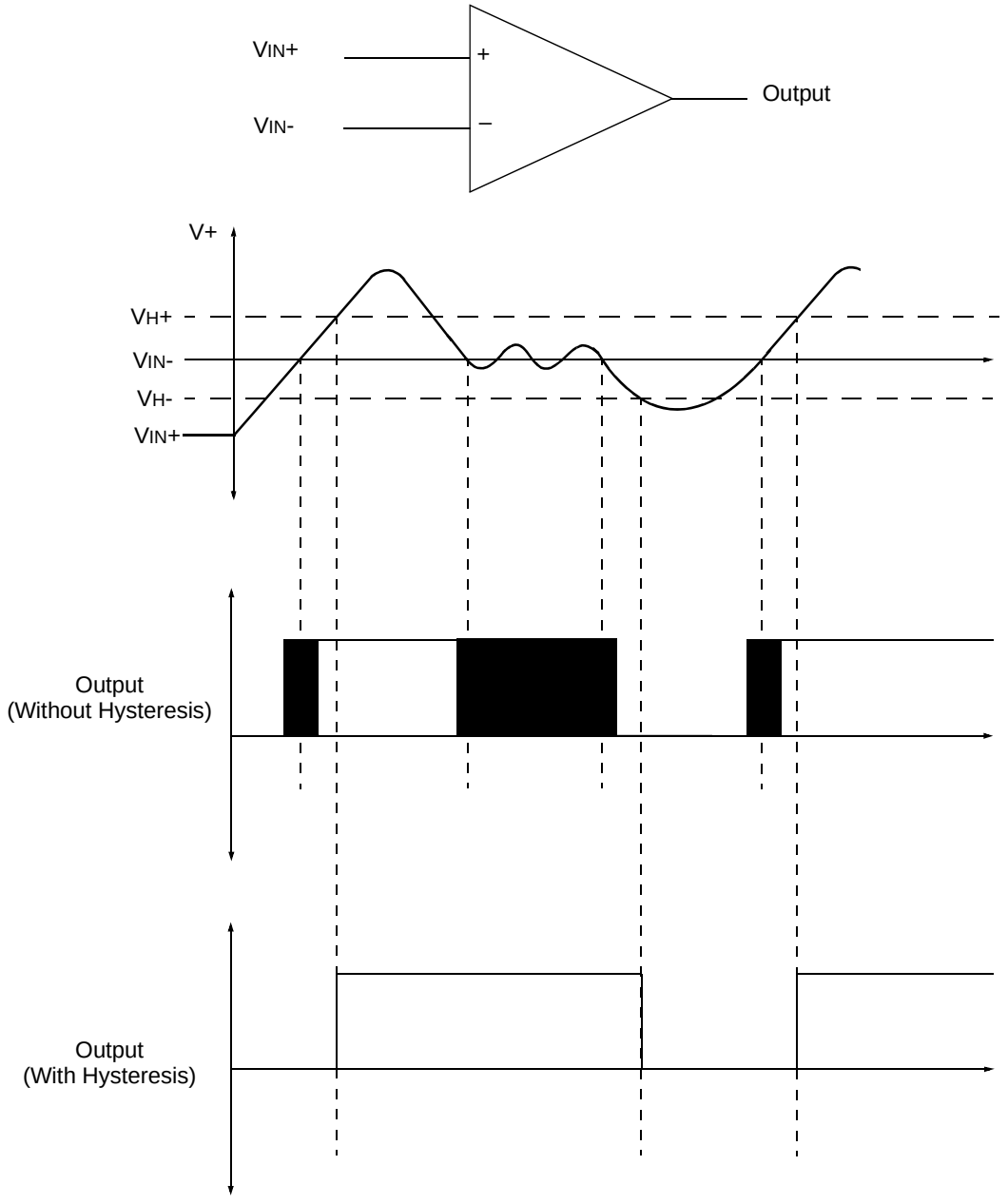
Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used for Timer2 module.
Note 1: For PIC12F615/617/HV615 only.

9.11 Comparator Hysteresis

Each comparator has built-in hysteresis that is user enabled by setting the CMHYS bit of the CMCON1 register. The hysteresis feature can help filter noise and reduce multiple comparator output transitions when the output is changing state.

Figure 9-7 shows the relationship between the analog input levels and digital output of a comparator with and without hysteresis. The output of the comparator changes from a low state to a high state only when the analog voltage at VIN+ rises above the upper hysteresis threshold (VH+). The output of the comparator changes from a high state to a low state only when the analog voltage at VIN+ falls below the lower hysteresis threshold (VH-).

FIGURE 9-7: COMPARATOR HYSTERESIS



Note: The black areas of the comparator output represents the uncertainty due to input offsets and response time.

12.0 SPECIAL FEATURES OF THE CPU

The PIC12F609/615/617/12HV609/615 has a host of features intended to maximize system reliability, minimize cost through elimination of external components, provide power-saving features and offer code protection.

These features are:

- Reset
  - Power-on Reset (POR)
  - Power-up Timer (PWRT)
  - Oscillator Start-up Timer (OST)
  - Brown-out Reset (BOR)
- Interrupts
- Watchdog Timer (WDT)
- Oscillator selection
- Sleep
- Code protection
- ID Locations
- In-Circuit Serial Programming

The PIC12F609/615/617/12HV609/615 has two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in Reset until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 64 ms (nominal) on power-up only, designed to keep the part in Reset while the power supply stabilizes. There is also circuitry to reset the device if a brown-out occurs, which can use the Power-up Timer to provide at least a 64 ms Reset. With these three functions-on-chip, most applications need no external Reset circuitry.

The Sleep mode is designed to offer a very low-current Power-Down mode. The user can wake-up from Sleep through:

- External Reset
- Watchdog Timer Wake-up
- An interrupt

Several oscillator options are also made available to allow the part to fit the application. The INTOSC option saves system cost while the LP crystal option saves power. A set of Configuration bits are used to select various options (see Register 12-1).

12.1 Configuration Bits

The Configuration bits can be programmed (read as '0'), or left unprogrammed (read as '1') to select various device configurations as shown in Register 12-1. These bits are mapped in program memory location 2007h.

Note:	Address 2007h is beyond the user program memory space. It belongs to the special configuration memory space (2000h-3FFFh), which can be accessed only during programming. See *Memory Programming Specification* (DS41204) for more information.

NOTES:

DECFSZ **Decrement f, Skip if 0**

Syntax: [*label*] DECFSZ f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - 1 → (destination);
skip if result = 0

Status Affected: None

Description: The contents of register 'f' are decremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.
If the result is '1', the next instruction is executed. If the result is '0', then a NOP is executed instead, making it a two-cycle instruction.

GOTO **Unconditional Branch**

Syntax: [*label*] GOTO k

Operands: $0 \le k \le 2047$

Operation: k → PC<10:0>
PCLATH<4:3> → PC<12:11>

Status Affected: None

Description: GOTO is an unconditional branch. The eleven-bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a two-cycle instruction.

INCF **Increment f**

Syntax: [*label*] INCF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) + 1 → (destination)

Status Affected: Z

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

INCFSZ **Increment f, Skip if 0**

Syntax: [*label*] INCFSZ f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) + 1 → (destination),
skip if result = 0

Status Affected: None

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.
If the result is '1', the next instruction is executed. If the result is '0', a NOP is executed instead, making it a two-cycle instruction.

IORLW **Inclusive OR literal with W**

Syntax: [*label*] IORLW k

Operands: $0 \le k \le 255$

Operation: (W) .OR. k → (W)

Status Affected: Z

Description: The contents of the W register are OR'ed with the eight-bit literal 'k'. The result is placed in the W register.

IORWF **Inclusive OR W with f**

Syntax: [*label*] IORWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .OR. (f) → (destination)

Status Affected: Z

Description: Inclusive OR the W register with register 'f'. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

TABLE 16-14: DC CHARACTERISTICS FOR IDD SPECIFICATIONS FOR PIC12F615-H (High Temp.)

Param No.	Device Characteristics	Units	Min	Typ	Max	Condition	
						VDD	Note
D010	Supply Current (IDD)	μA	—	13	58	2.0	IDD LP OSC (32 kHz)
			—	19	67	3.0	
			—	32	92	5.0	
D011		μA	—	135	316	2.0	IDD XT OSC (1 MHz)
			—	185	400	3.0	
			—	300	537	5.0	
D012		μA	—	240	495	2.0	IDD XT OSC (4 MHz)
			—	360	680	3.0	
		mA	—	0.660	1.20	5.0	
D013		μA	—	75	158	2.0	IDD EC OSC (1 MHz)
			—	155	338	3.0	
			—	345	792	5.0	
D014		μA	—	185	357	2.0	IDD EC OSC (4 MHz)
			—	325	625	3.0	
		mA	—	0.665	1.30	5.0	
D016		μA	—	245	476	2.0	IDD INTOSC (4 MHz)
			—	360	672	3.0	
			—	620	1.10	5.0	
D017		μA	—	395	757	2.0	IDD INTOSC (8 MHz)
		mA	—	0.620	1.20	3.0	
			—	1.20	2.20	5.0	
D018		μA	—	175	332	2.0	IDD EXTRC (4 MHz)
			—	285	518	3.0	
			—	530	972	5.0	
D019		mA	—	2.20	4.10	4.5	IDD HS OSC (20 MHz)
			—	2.80	4.80	5.0	

TABLE 16-18: OSCILLATOR PARAMETERS FOR PIC12F615-H (High Temp.)

Param No.	Sym	Characteristic	Frequency Tolerance	Units	Min	Typ	Max	Conditions
OS08	INTOSC	Int. Calibrated INTOSC Freq.(1)	±10%	MHz	7.2	8.0	8.8	2.0V ≤ VDD ≤ 5.5V -40°C ≤ TA ≤ 150°C

Note 1: To ensure these oscillator frequency tolerances, Vdd and Vss must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

TABLE 16-19: COMPARATOR SPECIFICATIONS FOR PIC12F615-H (High Temp.)

Param No.	Sym	Characteristic	Units	Min	Typ	Max	Conditions
CM01	VOS	Input Offset Voltage	mV	—	±5	±20	(VDD - 1.5)/2

FIGURE 17-6: PIC12F609/615/617 IDD INTOSC (4 MHz) vs. VDD

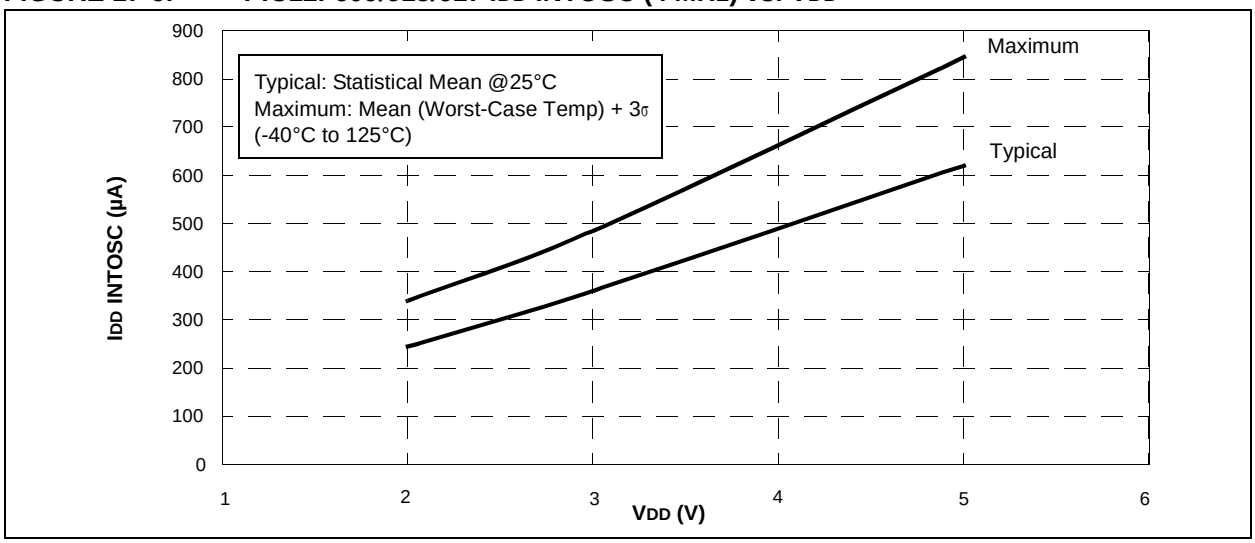


FIGURE 17-7: PIC12F609/615/617 IDD INTOSC (8 MHz) vs. VDD

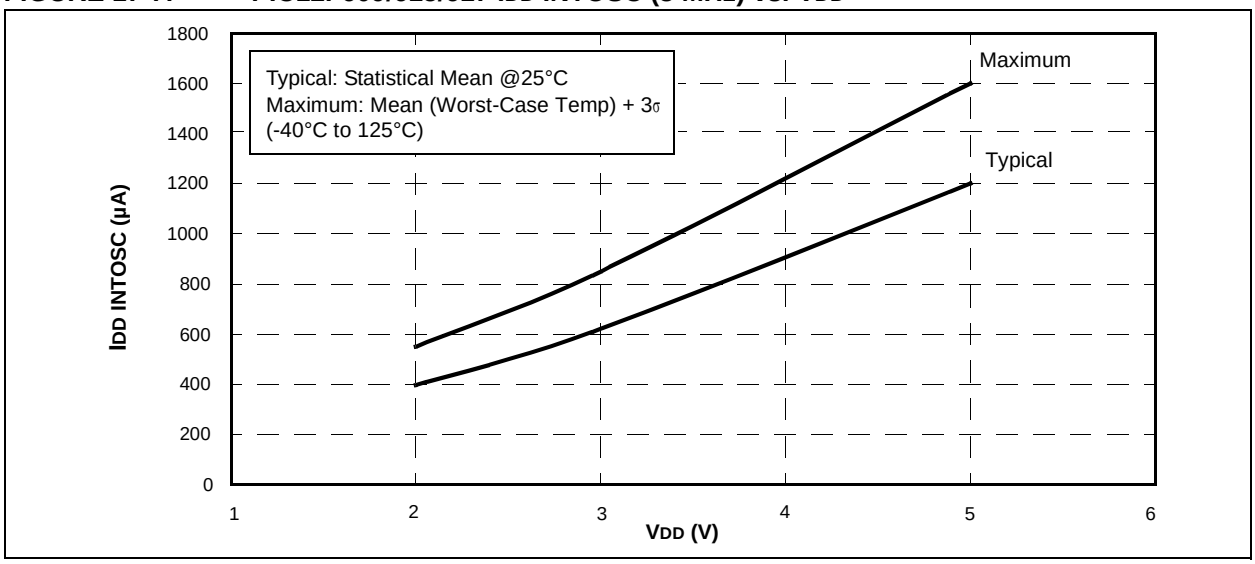


FIGURE 17-14: PIC12F609/615/617 IPD CVREF (LOW RANGE) vs. VDD

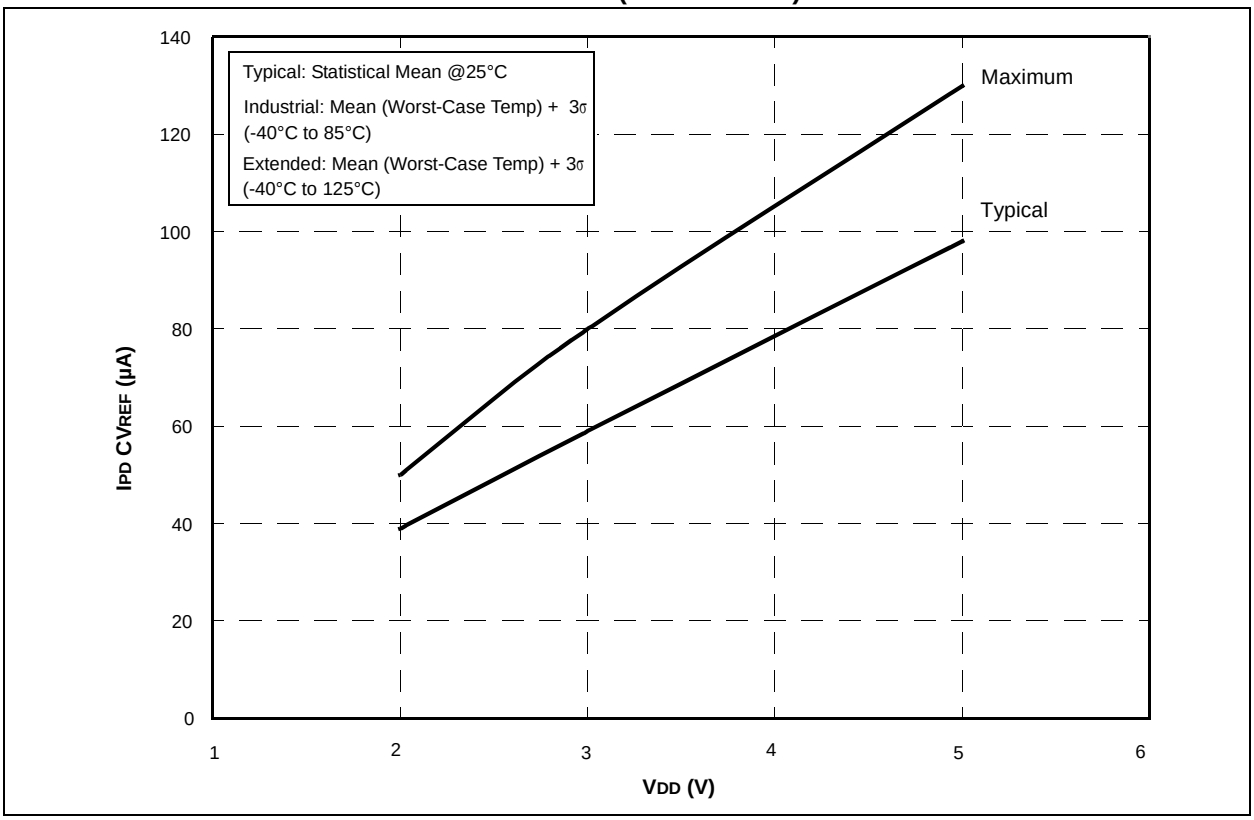


FIGURE 17-15: PIC12F609/615/617 IPD CVREF (HI RANGE) vs. VDD

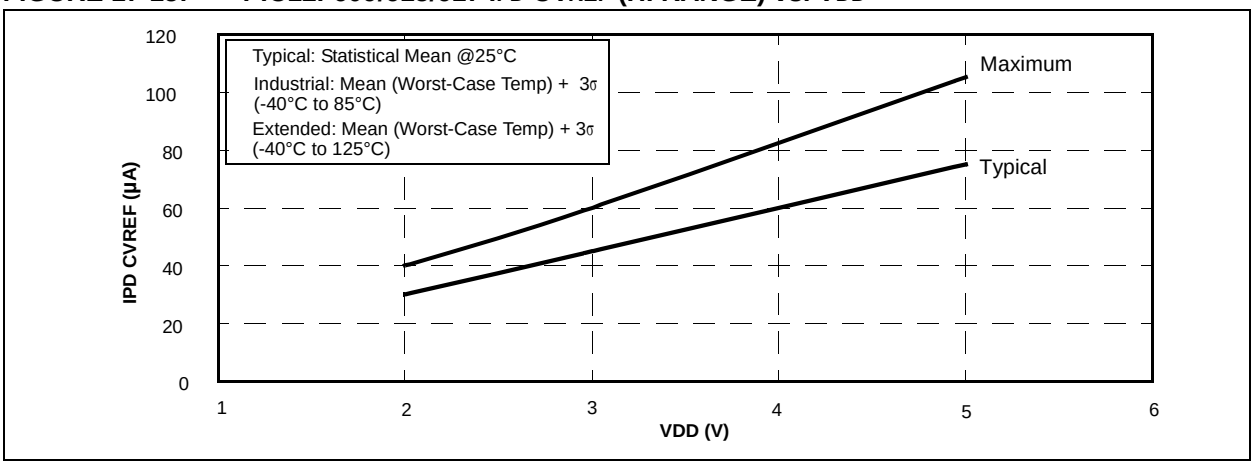


FIGURE 17-27: PIC12HV609/615 IPD COMPARATOR (SINGLE ON) vs. VDD

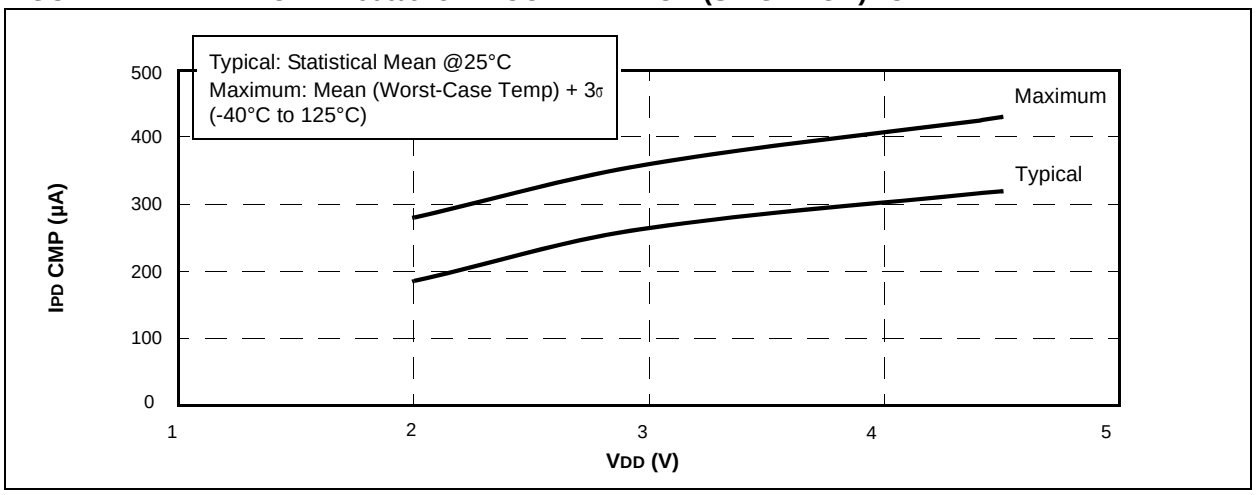


FIGURE 17-28: PIC12HV609/615 IPD WDT vs. VDD

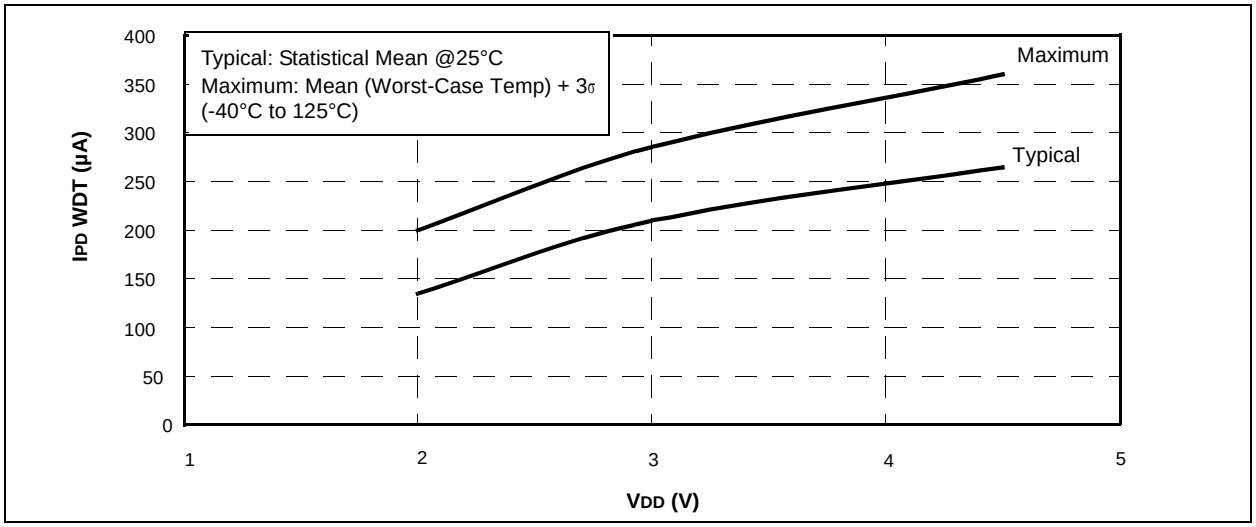


FIGURE 17-29: PIC12HV609/615 IPD BOR vs. VDD

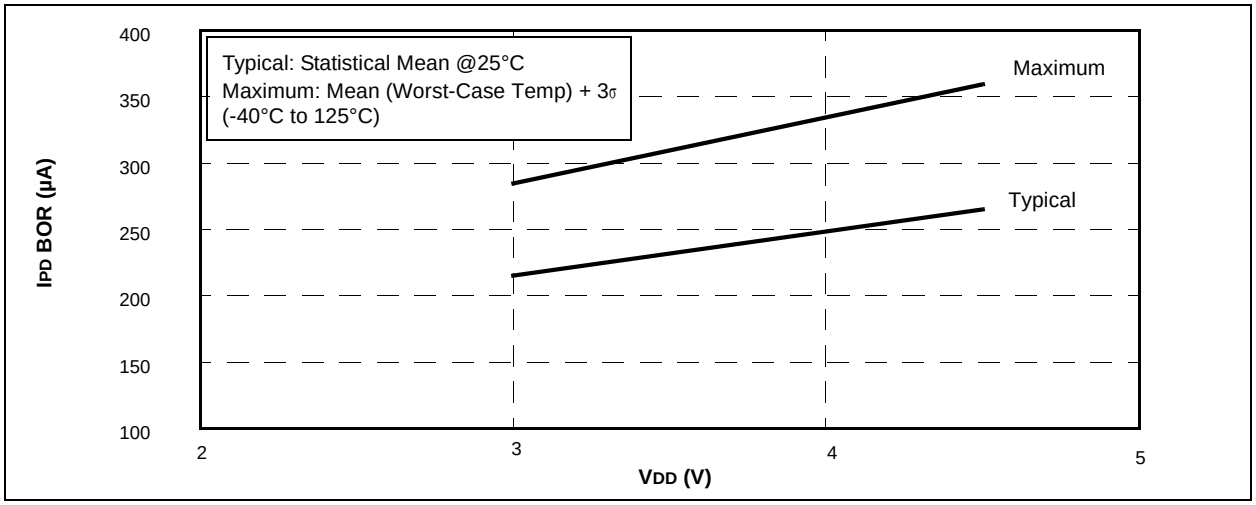


FIGURE 17-45: TYPICAL HFINTOSC FREQUENCY CHANGE vs. VDD (125°C)

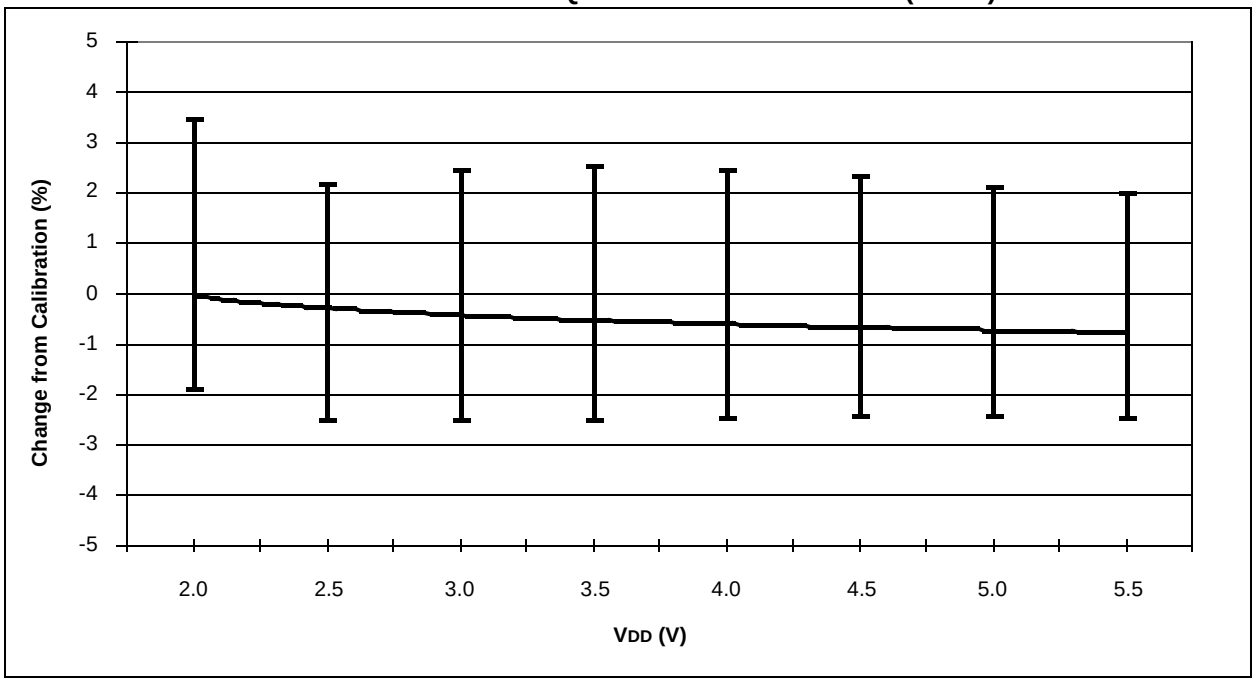


FIGURE 17-46: TYPICAL HFINTOSC FREQUENCY CHANGE vs. VDD (-40°C)

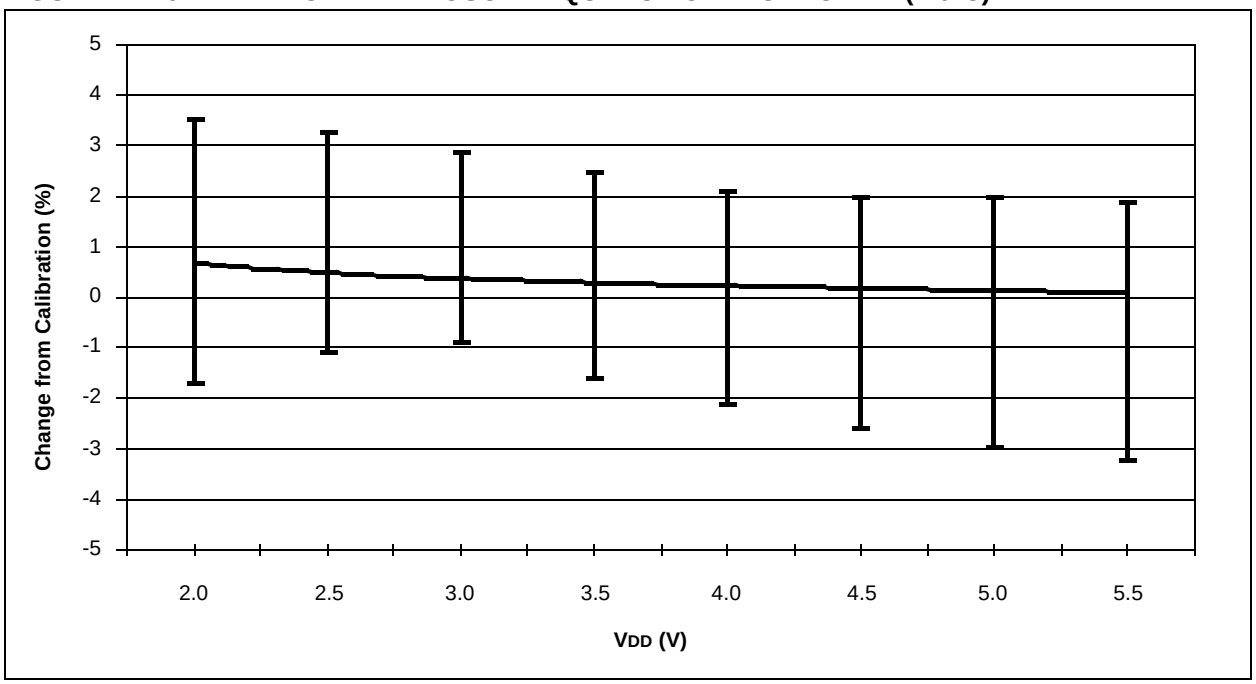


FIGURE 17-47: 0.6V REFERENCE VOLTAGE vs. TEMP (TYPICAL)

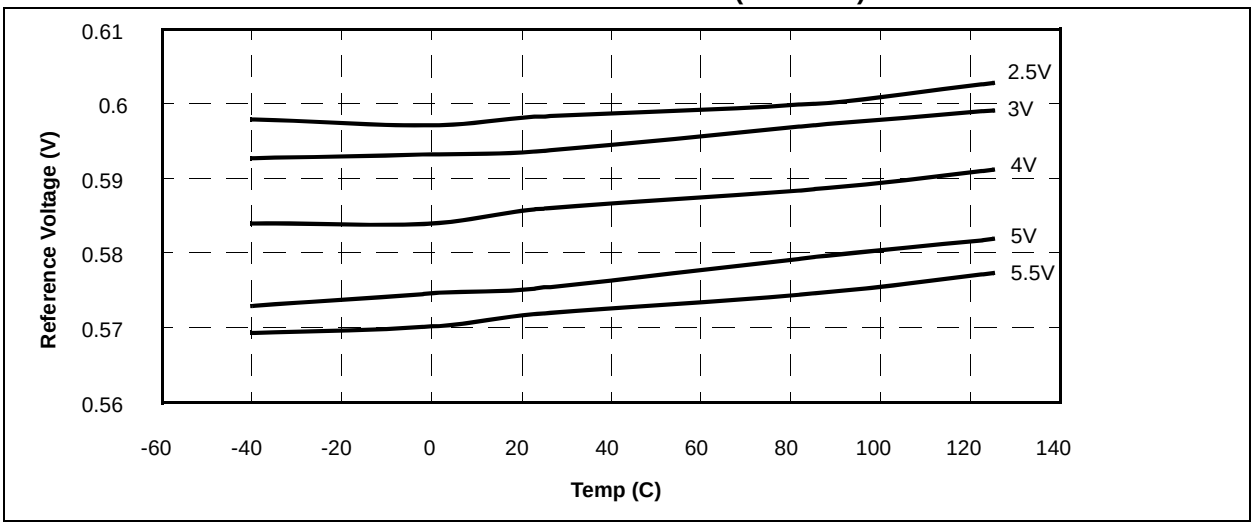


FIGURE 17-48: 1.2V REFERENCE VOLTAGE vs. TEMP (TYPICAL)

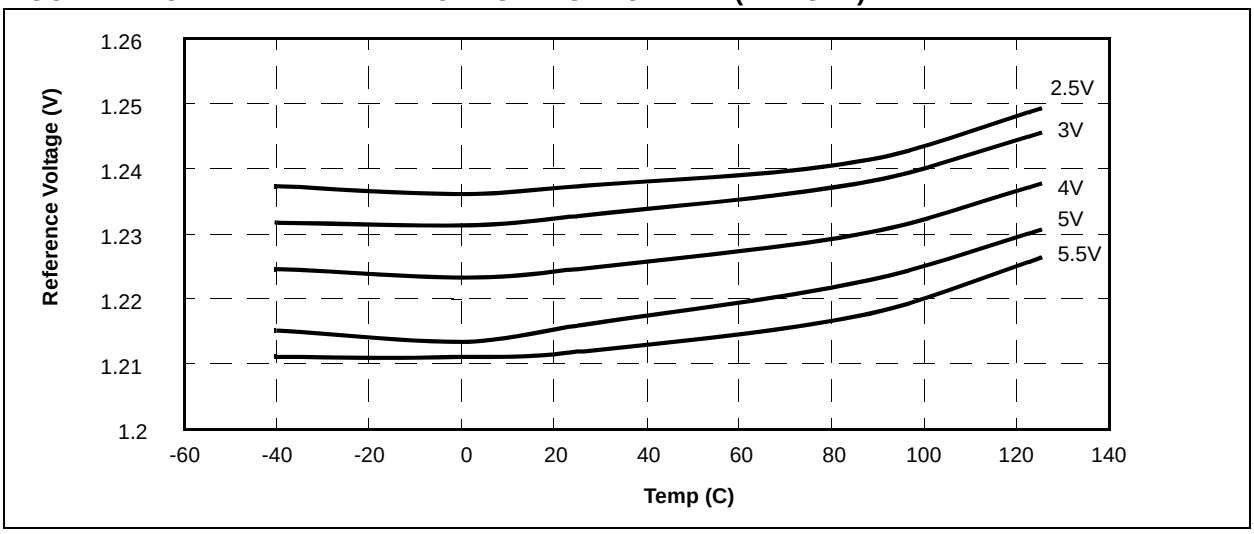
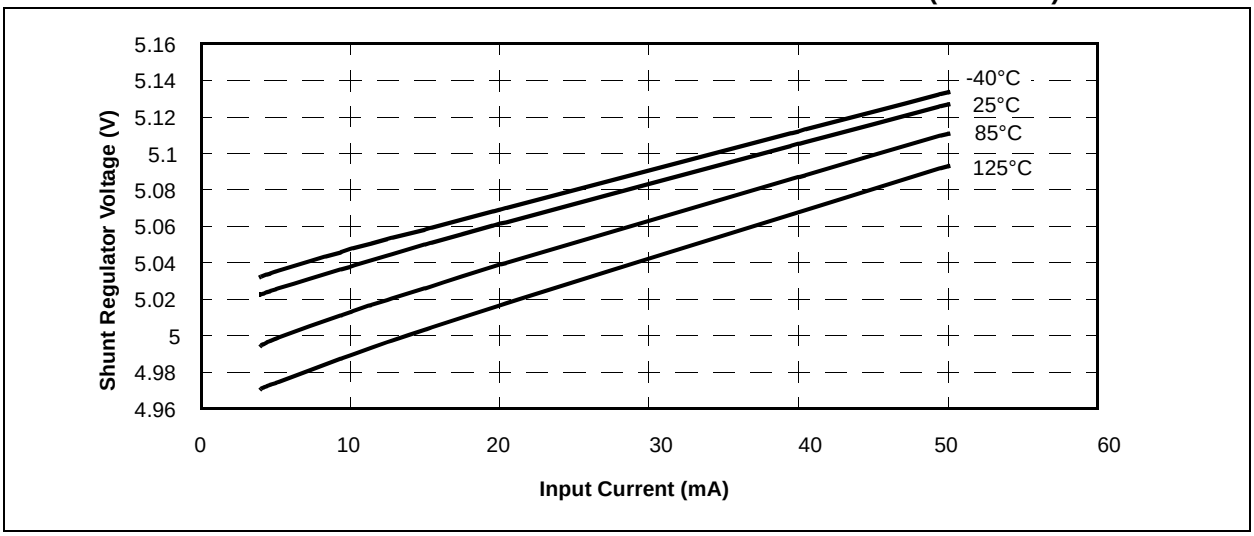
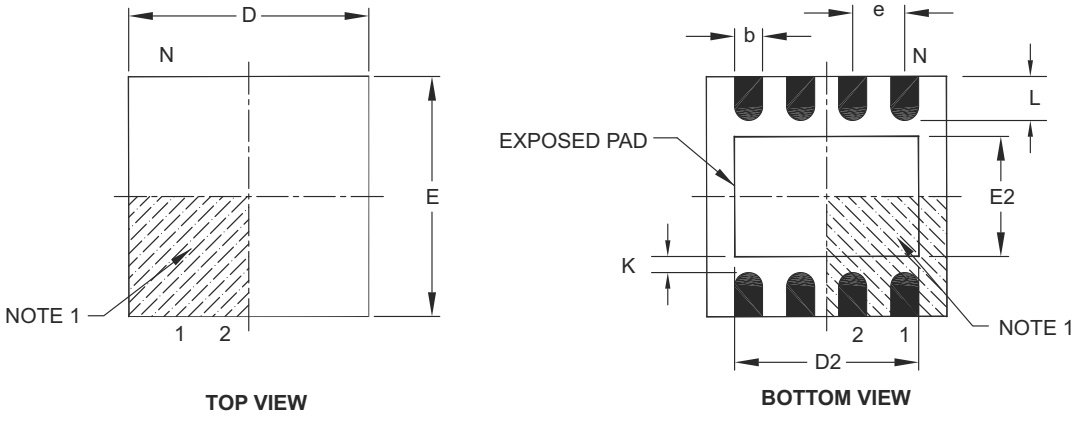


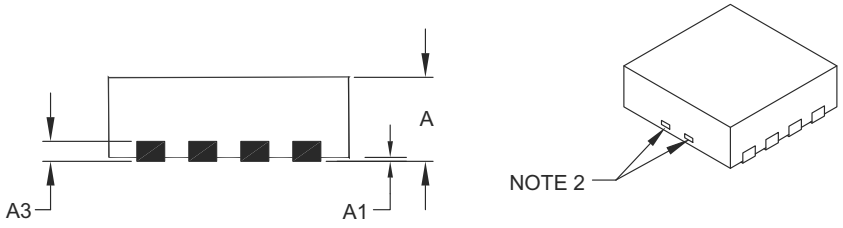
FIGURE 17-49: SHUNT REGULATOR VOLTAGE vs. INPUT CURRENT (TYPICAL)



8-Lead Plastic Dual Flat, No Lead Package (MF) – 3x3x0.9 mm Body [DFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Length	D		3.00 BSC	
Exposed Pad Width	E2	0.00	–	1.60
Overall Width	E		3.00 BSC	
Exposed Pad Length	D2	0.00	–	2.40
Contact Width	b	0.25	0.30	0.35
Contact Length	L	0.20	0.30	0.55
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

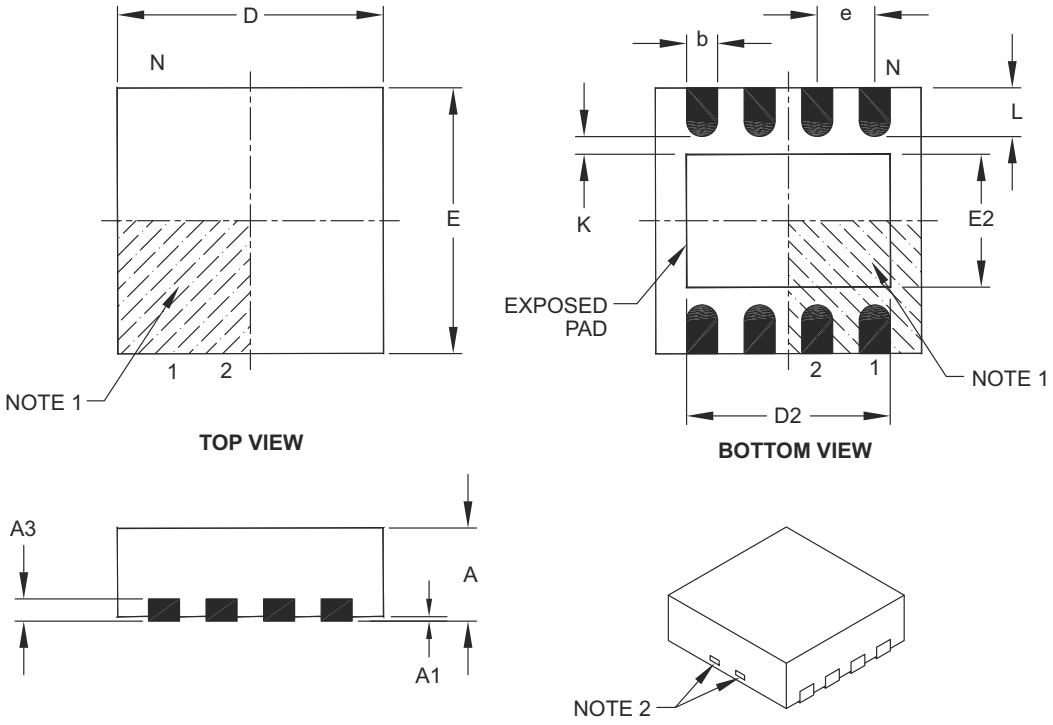
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package may have one or more exposed tie bars at ends.
3. Package is saw singulated.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-062B

8-Lead Plastic Dual Flat, No Lead Package (MD) – 4x4x0.9 mm Body [DFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		0.80 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Length	D		4.00 BSC	
Exposed Pad Width	E2	0.00	2.20	2.80
Overall Width	E		4.00 BSC	
Exposed Pad Length	D2	0.00	3.00	3.60
Contact Width	b	0.25	0.30	0.35
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package may have one or more exposed tie bars at ends.
3. Package is saw singulated.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-131D